IPC ASSOCIATION ELECTRONIC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Typ  http://www.ipc.org/IPC-175x  Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information				
upplie	r Information														
Company	name*	Company unique ID			U	Unique ID Authority				Resp	Response Date*				
onsemi											2025	2025-06-06			
Contact N	ame	Title - Contact			P	Phone - Contact*				Ema	Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance			1	NA				Proc	Product-Env-Stewards@onsemi.com			
uthorize	d Representative*		Title - Representative			P	Phone - Representative*				Ema	Email - Representative*			
Product-l	Env-Stewards		Product Enviro Compliance			1	NA				Proc	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	te Version Manufacturing Site		Site	Weight*	UOM	Unit Type		
		FQD10N20LTM QF 200V 360mOh		ım L DAPK		2025-06-06 CPA			291.831	mg	Each				
Ianufa	cturing Proccess Inform	ation												·	
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-		-STD-020 MSL F	Rating	Peak Process Body Temperatur		Max Time a	t Peak Temp	erature Numb	er of Reflow Cyo	eles		
Matte Tin (Sn) - annealed CU			CU Alloy	1			260		C	30	se	conds 3			
omments															
<u>vel 1 - m</u>	aximum time at peak tempera	ture during so	ldering is 10	30 seconds											
or more	information regarding materia	al composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.93	mg	Supplier	Silicon (Si)	7440-21-3		5.93	mg
Die Attach Solder	2.353		Supplier	Silver (Ag)	7440-22-4		0.0588	mg
			A	Lead (Pb)	7439-92-1	7a	2.1765	mg
			Supplier	Tin (Sn)	7440-31-5		0.1176	mg
Lead Frame	150.208		Supplier	Tin (Sn)	7440-31-5		0.16	mg
			В	Nickel (Ni)	7440-02-0		0.048	mg
			Supplier	Copper (Cu)	7440-50-8		150	mg
Mold Compound-Black	129.0	mg		Epoxy resin	proprietary data		7.74	mg
			Supplier	Phenolic Resin	Proprietary Data		7.74	mg
			Supplier	Carbon Black (C)	1333-86-4		0.645	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		109.65	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.225	mg
Plating	1.9	mg	Supplier	Tin (Sn)	7440-31-5		1.9	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg